

20 – 50 PIECE TRAY  
MODULE ORIENTATION A (HORIZONTAL)

JEDEC SOLID STATE  
PRODUCT OUTLINE  
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AND REFLECTS A PRODUCT WITH ANTICIPATED USAGE IN THE ELECTRONICS INDUSTRY;  
CHANGES ARE LIKELY TO OCCUR.

TITLE SHIPPING AND HANDLING  
TRAY FOR M.2 TYPE 2230  
MICROELECTRONIC ASSEMBLY

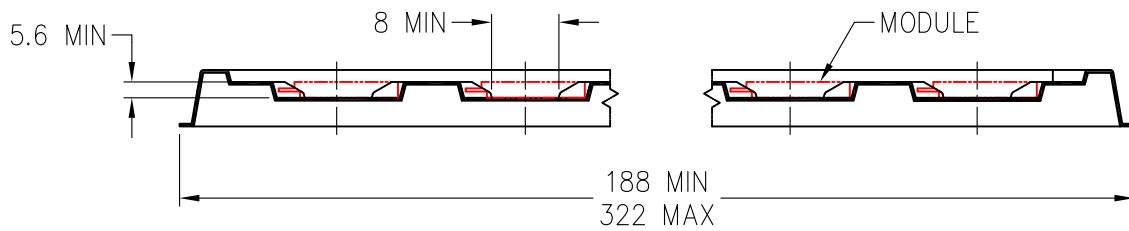
PACKAGE DESIGNATOR  
N/A

ITEM  
CO-039

ISSUE  
A

DATE  
APR 2023

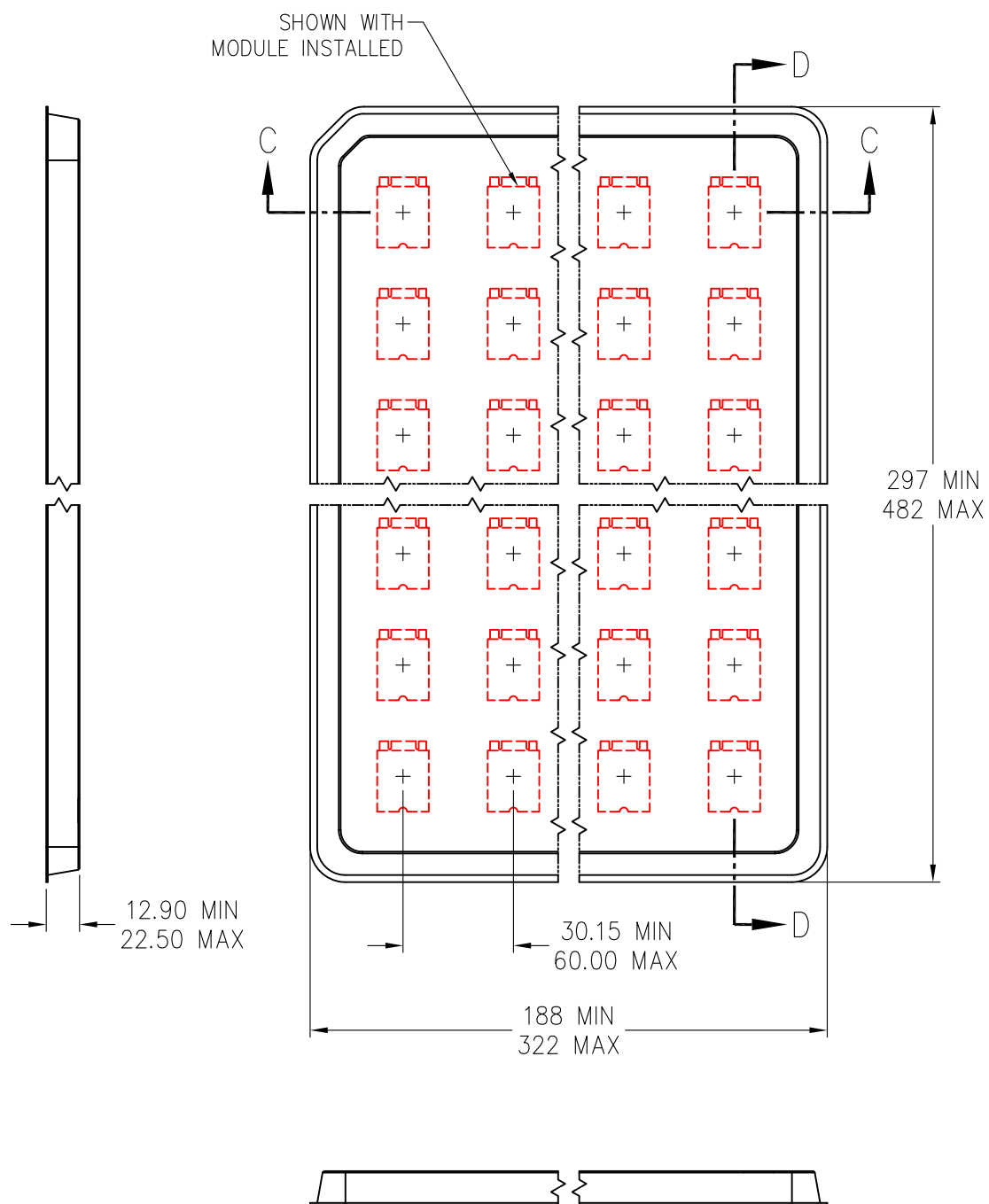
SHEET  
1 OF 5



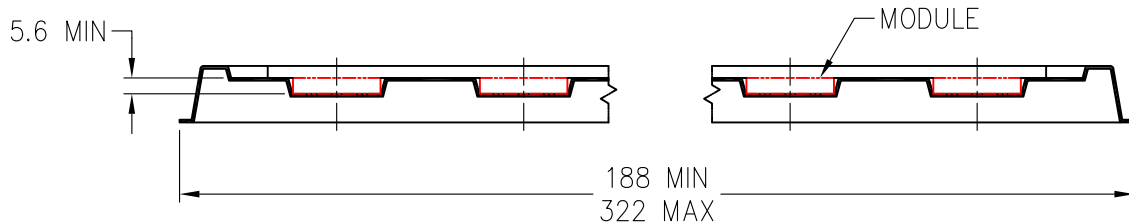
SECTION A-A



SECTION B-B (ROTATED 90° CCW)



20 – 50 PIECE TRAY  
MODULE ORIENTATION B (VERTICAL)



SECTION C-C



SECTION D-D (ROTATED 90° CCW)

# VARIATION DIMENSIONS ARE IN MILLIMETERS

VARIATION	PACKAGE BODY SIZE	QUANTITY PER TRAY
M.2 TYPE 2230	22mm X 30mm	20 – 50

## NOTES:

1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5–2009.
2. ALL DIMENSIONS ARE MILLIMETERS.  
THIS DIMENSION IS EXPECTED TO BE CONSTANT BETWEEN THE ROWS OF THE TRAY
3. THIS TRAY IS DESIGNED SPECIFICALLY TO FIT PCI–SIG STANDARD,  
M.2 TYPE 2230 PITCH MICROELECTRONIC ASSEMBLY
4. MODULE ORIENTATION CAN BE HORIZONTAL TO THE LENGTH OR WIDTH OF THE TRAY.  
THE SHAPES SHOWN IN THIS DRAWING ARE EXAMPLES AND ANY SHAPE WITHIN THE DIMENSION IS ACCEPTABLE.

STP (3D) FILE RECORD  
3D FILE NAMES MAY EXCEED LENGTH REQUIREMENTS FOR SOME SOFTWARE TOOLS.

STP FILE NAME	DATE	ITEM NUMBER
CO-039A_SHIPPING AND HANDLING TRAY FOR M.2 TYPE 2230 SSD (20 – 50 PCS) –MODULE ORIENTATION A (HORIZONTAL)	APR 2023	5–1004
CO-039A_SHIPPING AND HANDLING TRAY FOR M.2 TYPE 2230 SSD (20 – 50 PCS)–MODULE ORIENTATION B (VERTICAL)	APR 2023	5–1004

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# CHANGE RECORD

IF THE CHANGE INVOLVES ANY WORDS ADDED OR DELETED (EXCLUDING DELETION OF ACCIDENTALLY REPEATED WORDS), THE CHANGE IS TO BE INCLUDED BELOW. PUNCTUATION CHANGES MAY OR MAY NOT BE INCLUDED.

INITIAL ISSUE: A	DATE: APRIL 2023	ITEM NUMBER: 5-1004
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CHANGE RECORD HISTORY:
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ISSUE: -	DATE: -	ITEM NUMBER: -
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LOCATION:	CHANGED FROM:	CHANGED TO: